

METHOD OF FABRICATING SUBSTRATES, IN PARTICULAR FOR
OPTICS, ELECTRONICS OR OPTOELECTRONICS

ABSTRACT

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A method of fabricating substrates while minimizing loss of starting material of an ingot, wherein a layer is transferred onto a support. The technique includes forming a flat front face on a raw ingot of material, 10 implanting atomic species through the front face to a controlled mean implantation depth to create a zone of weakness that defines a top layer of the ingot, bonding a support to the front face of the ingot, wherein the support has a surface area that is smaller than a surface 15 area of the front face of the ingot, and detaching from the ingot at the zone of weakness that portion of the top layer that is bonded to the support to form the substrate.

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